

DK-US030324



IFW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hiromune MATSUOKA et al.

Serial No.: 10/560,621

Filed: December 14, 2005

For: REFRIGERATION APPARATUS
CONSTRUCTING METHOD, AND
REFRIGERATION APPARATUS

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner of Patents
Washington, DC 20231

Sir:

In accordance with MPEP 609 and 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicants bring the attached references to the Examiner's attention and request that they be considered and made of record in this application. Also attached is a completed PTO-1449 form. *No fee is believed to be due for this Information Disclosure Statement.* However, if a first Office Action on the merits was mailed before the filing date of this Information Disclosure Statement, the Commissioner is authorized to charge the fee set forth in 37 CFR § 1.17(p) to Deposit Account No. 50-1836. A duplicate copy of this Statement is enclosed for that purpose.

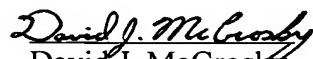
Japanese Utility Model Publication No. 01-88364 appears to disclose a heat pump refrigeration cycle having a receiver connected to an upper side of a refrigerant connecting pipe connecting between a condenser and an expansion valve, and an air discharging valve connected to an upper side of the receiver.

Japanese Patent Publication No. 45-17704 appears to disclose a heating device including a heat exchange circuit having a condenser, an expansion valve and a receiver provided between the condenser and the expansion valve, and a noncondensable gas storage connected to the receiver and containing a noncondensable gas having higher volatility than that of a refrigerant. The noncondensable gas storage supplies the noncondensable gas into the heat exchange circuit when a vapor pressure of the refrigerant in the condenser increases

and removes the noncondensable gas from the heat exchange circuit when the vapor pressure decreases.

Prompt examination on the merits is respectfully requested.

Respectfully submitted,


David J. McCrosky
Reg. No. 56,232

GLOBAL IP COUNSELORS, LLP
1233 Twentieth Street, NW, Suite 700
Washington, DC 20036
(202)-293-0444

Dated: January 23, 2007

G:\01-JAN07-YTY\DK-US030324 IDS.doc



PTO/SB/08A (10-01)

Approved for use through 10/31/2002. OMB 0651-0031

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

~~Substitute for form 1449A/PTO~~

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet

of

Complete if Known

Application Number	10/560,621
Filing Date	December 14, 2005
First Named Inventor	Hiromune MATSUOKA
Group Art Unit	
Examiner Name	
Attorney Docket Number	DK-US030324

Sheet

of

DK-US030324

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

Examiner Signature		Date Considered	
-----------------------	--	--------------------	--

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04.

³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.